FORM PTO-1594 1-31-92



U.S. Department of Commerce Patent and Trademark Office Attorney Docket No. 03180.0280

1-31-92

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			of Patents a nal documents or			ATTN. BC	X ASSIG	NMENTS	2	
2. Su 3. Te 4. Hid	Name of conveying parties: 1. Masatoshi FUKUDA 2. Susumu HARADA 3. Tetsuya SATO 4. Hidenobu SATO 5. Atsushi NAKANO					2. Name and address of receiving party(ies):				
					Name:	KABUSHI	KI KAISH	IA TOSHIBA		
Addition	nal name	(s) of conveying pa	arty(ies) attached?	□ Yes ⊠ No	Internal A	ddress:				
3.	Nature	of conveyance:			Street Address: 72 Horikawa-cho, Saiwai-ku Kawasaki-shi, Japan					
					City:	<u> </u>			T	
⊠		Assignment -		Merger	State:	1		Zip Code:		
		Security Agreement		Change of Name						
		Other								
					Additiona	I name(s) & A	Address(e	es) attached?		
Execution	on Date:	May 10, 2001			□ Yes ⊠ N	No				
4.		tion number(s) or p tion: <u>May 10, 2001</u>	patent number(s): If	f this document is be	eing filed to	gether with a	new app	lication, the ex	ecution date of the	
A.	Patent A	Application Numbe	er(s):		B. Patent	t Number(s):				
	091	855529								
	. , .	,	Addit	tional numbers attac	hed? □ Yes	s ⊠ No				
5.	Name and address of party to whom correspondence concerning document should be mailed:					6. Total number of applications and registrations involved:				
Name:	Mr En	nest F. Chapman			7. s	Total fee (37	CFR 3.41): \$40		
ivame.	IVII. ETI		ENDERCON EAD	ADOM CARRETT	1	(-				
Internal	Address		ENDERSON, FARA L.P.	ABOW, GARRETT	Enclosed	(Please chai	rge deficie	ency to deposi	t account)	
					Authorize	d to be charg	ged to dep	oosit account		
Street A	ddress:	1300 Street, I	N.W.			·····			8	
City:		Washington			8. (Deposit acco	unt numb	er: <u>06-0916</u>	85.0 4	
State:	_	DC	Zip: 2000	5-3315					998555299	
9.	To the !	ent and signature. best of my knowled document.	ge and belief, the t	foregoing informatio	n is true and	d correct and	l any atta	ched copy is a	15	
		Richard V. Burgu	jian	AR	, /	May	16, 2001	******	MAKEN1	
		Reg. No. 31	,744	Signa	ture			Date	.	
		Total	number of pages ir	ncluding cover shee	t, attachmei	nts and docu	ments:	3	7/2001	

PATENT

REEL: 011817 FRAME: 0551

SOLE/JOINT INVENTION (U.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled: SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, RESIN MOLDING DIE, AND SEMICONDUCTOR MANUFACTURING for which I/WE executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters

Patent on _____ (Serial No _____); and __, _____); and Patent on ____ WHEREAS, KABUSHIKI KAISHA TOSHIBA a corporation of ___Japan , whose post office address is 72 Horikawa-cho, Saiwai-ku, Kasawaki-shi, Kanagawa-ken, Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application; NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment; AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns. AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed __ _____) the filing date and application number of said application when known. IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s). 1. Full Name of Sole or First Assignor: Assignor's Signature : Date . May 10,2001 Masatoshi FUKUDA : mosatoshi Trubuda Address : Citizenship Kanagawa-ken,Japan : Japan 2. Full Name of Second Assignor : Assignor's Signature
Susumu HARADA : Susumu Harada : Date . May 10,2001 Address : Citizenship Kanagawa-ken, Japan Kanagawa-κουγοσμ 3. Full Name of Third Assignor : Assignor's Signature : Τειριμ Sατο : Japan : Date : May 10,2001

FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P. WASHINGTON, D.C.

Address

Mie-ken,Japan

PATENT REEL: 011817 FRAME: 0552

: Citizenship

: Japan

RECORDED: 05/16/2001

4. Full Name of Fourth Assignor Hidenobu SATO	: Assignor's Signature : Hi d enaby Tato	: Date : May 10,2001
Address Kanagawa-ken,Japan	•	: Citizenship : Japan
5. Full Name of Fifth Assignor Atsushi NAKANO	: Assignor's Signature : <i>Atouchi Natura</i>	: Date : May 10,2001
Address Kanagawa-ken,Japan		: Citizenship : Japan
6. Full Name of Sixth Assignor	: Assignor's Signature :	: Date
Address		: Citizenship
7. Full Name of Seventh Assignor	: Assignor's Signature :	: Date
Address		: Citizenship
8. Full Name of Eighth Assignor	: Assignor's Signature	: Date
Address	· · · · · · · · · · · · · · · · · · ·	: Citizenship
9. Full Name of Ninth Assignor	: Assignor's Signature	: Date
Address	•	: Citizenship
10.Full Name of Tenth Assignor	: Assignor's Signature	: Date
Address		: Citizenship
11.Full Name of Eleventh Assignor	: Assignor's Signature :	: Date
Address		: Citizenship
12.Full Name of Twelfth Assignor	: Assignor's Signature	: Date
Address		: Citizenship

PATENT REEL: 011817 FRAME: 0553